

CALICE: Thermal, Mechanical and Assembly issues

What Manchester could contribute

UCL Wednesday 10th November 2004

Manchester and Silicon

- Part of ATLAS SCT construction
 - Thermal design: simulation and testing
 - Assembly of 650 silicon modules
 - Survey, I-V, readout tests
 - Production database and QA

'Challenges' of CALICE build

- Testing detectors before assembly
 - Silicon characteristics
 - Identify and remember dead cells (if simulations show we are able to use “2nd quality Silicon”)
 - Do this in automatic or semiautomatic system (for prototype and for the full detector)

Challenges (contd)

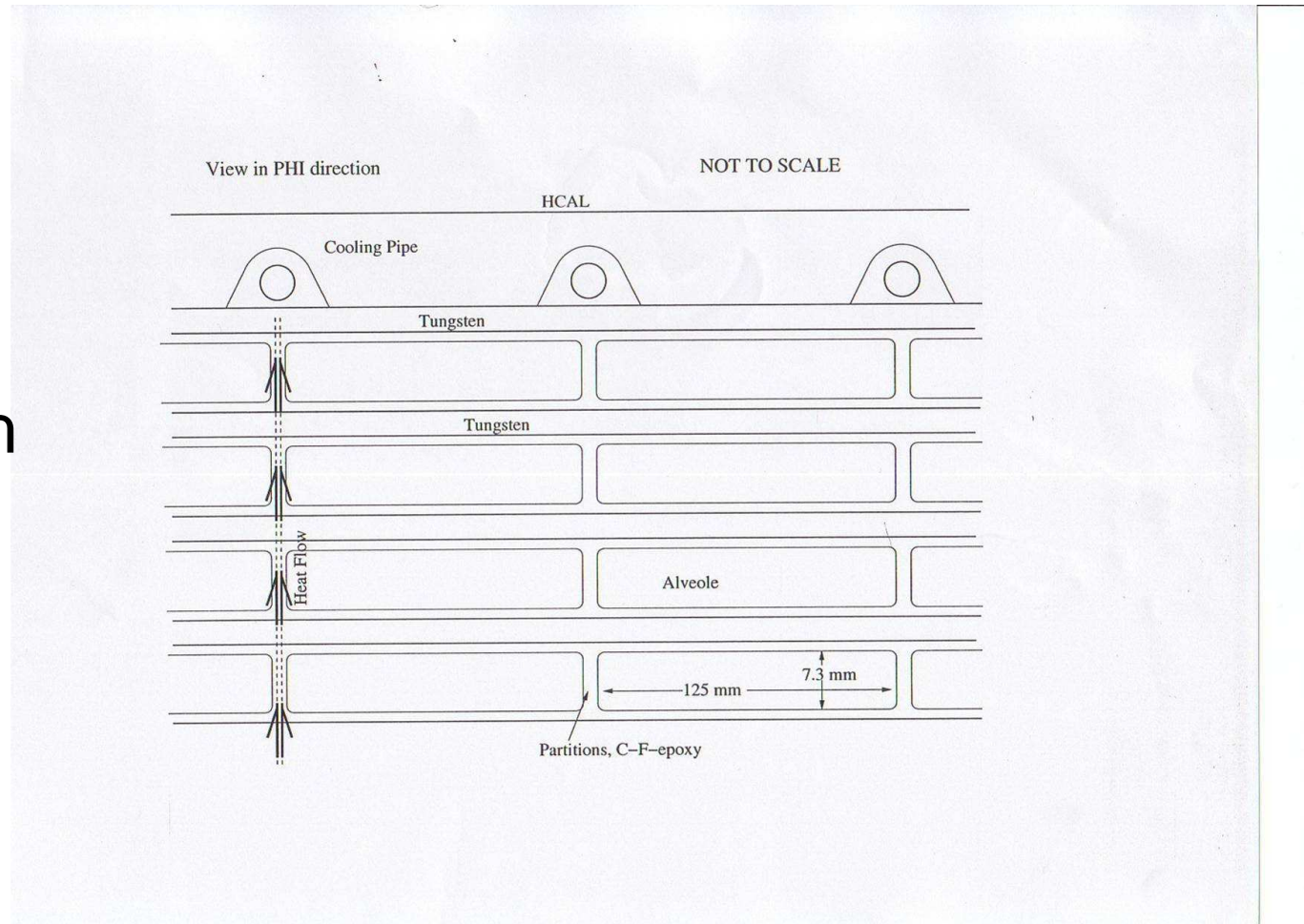
- Mount detectors on substrate
 - Check for flatness and mechanical tolerances
 - Know where the detectors are on the PCB
 - Know where the PCB is inside the module.
Location pins?
 - Check connectors all made properly
- Check the Tungsten
 - Metal sheets: Flatness? Thickness? Exact size
- Macro assemble of complete module

Thermal Issues

- Heat generated by electronics
 - What about MAPS? How many watts?
 - Can we put the preamps on the detector? Even if we can't, the electronics cooling needs doing properly.
 - Heat flows away – thermal conductivity in Silicon, Tungsten and Carbon Fibre (non-isotropic). Cooling blocks/cooling pipes
 - Studies using FLEXPDE package (we have experience and licence)

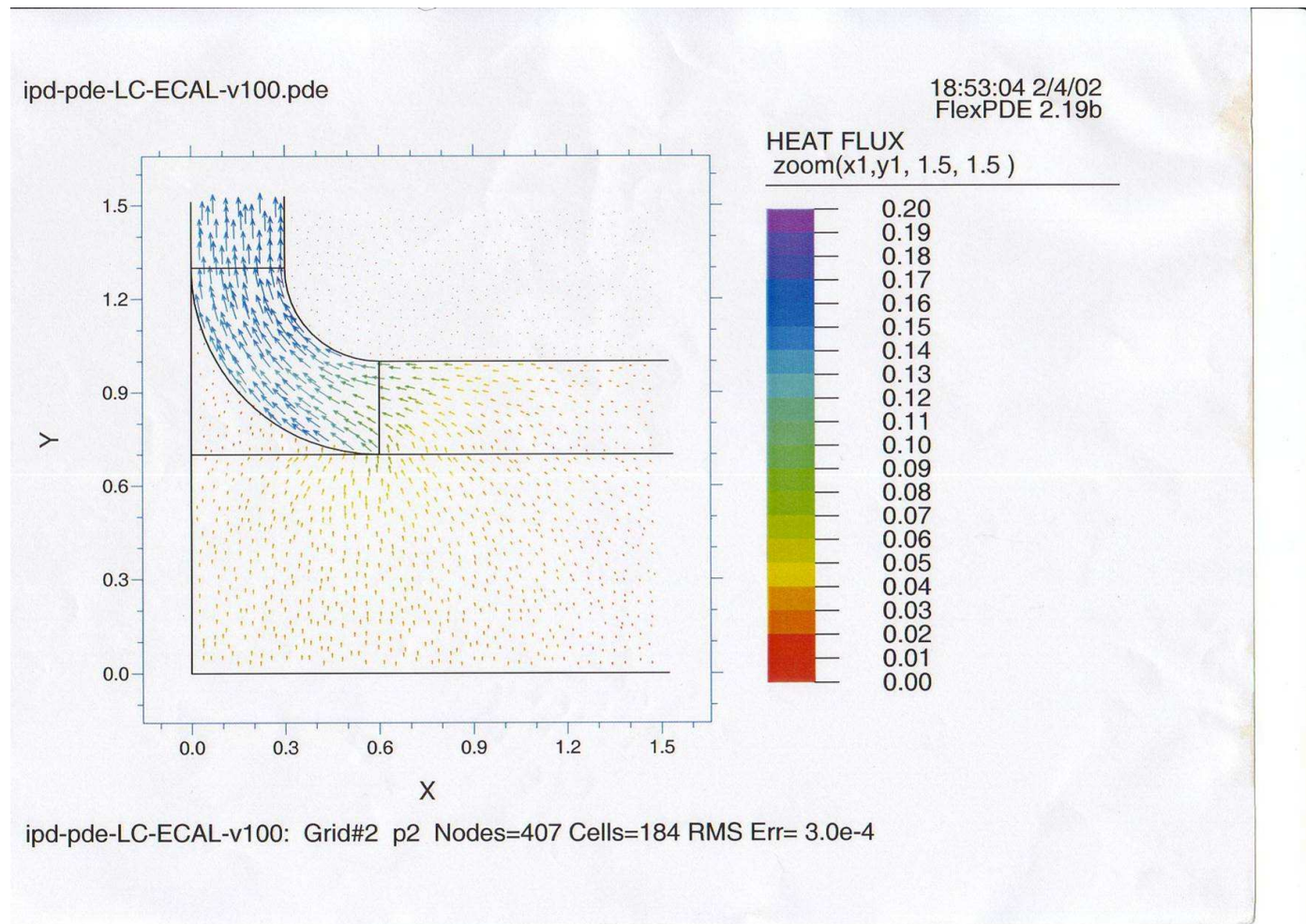
Heat flow through Tungsten and Carbon Fibre

Studies by
Ian Duerdoth
(previously
shown).
Could be
continued



Heat Flow

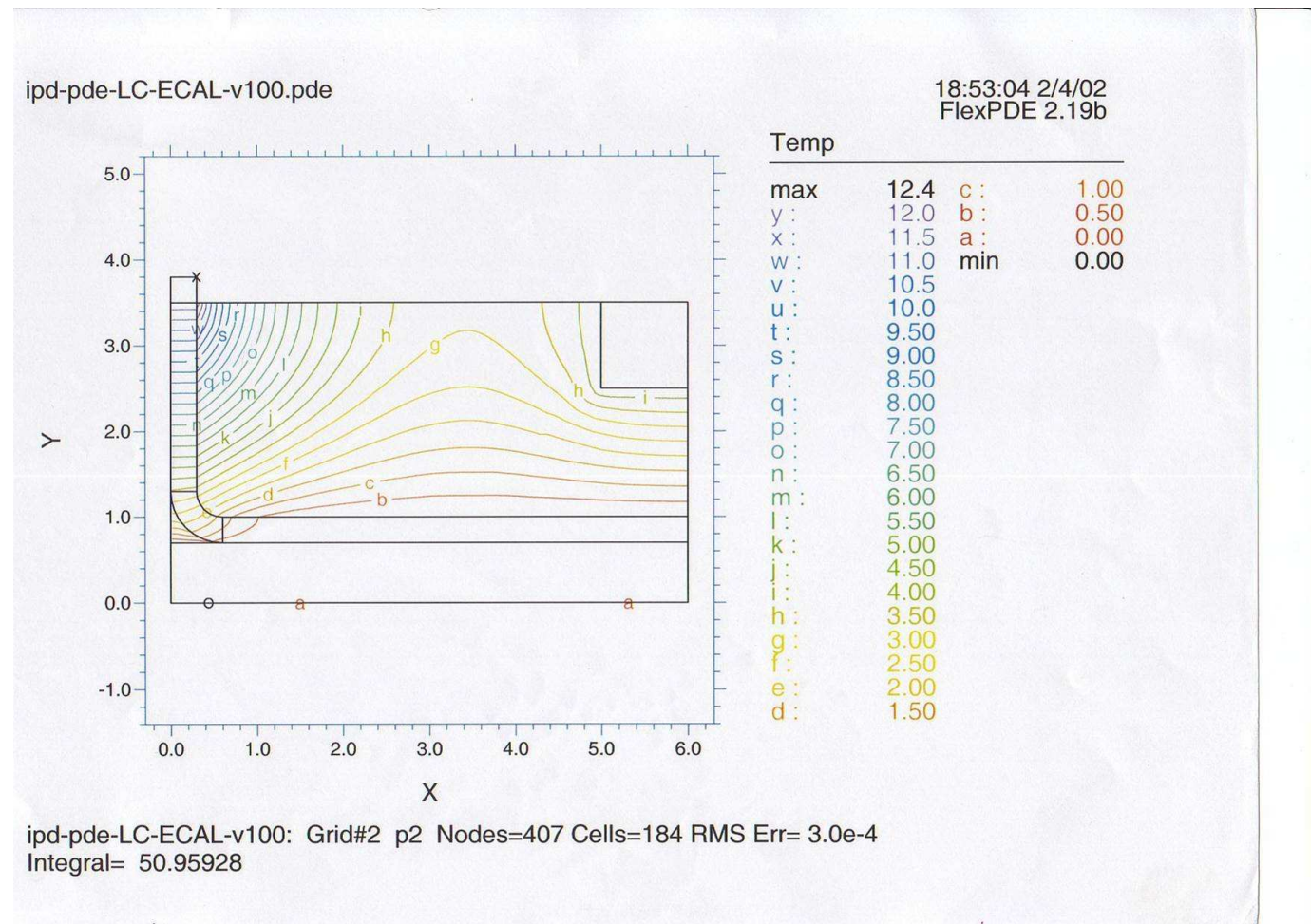
This is one corner.



Temperature

Isotherms.
Various possible scenarios

Now we know the technology – can we ramp the electronics HV up and down with the beam structure?



Conclusions

- These are only first thoughts
- Moving from concept to the real thing always raises lots of practical issues
- Manchester has long detector-building tradition and experience. We've been through this cycle many times and know what sort of problems to anticipate
- Anticipation and understanding can be crucial to success